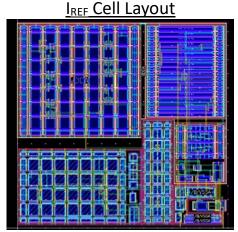


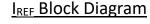
## IREF7 (internal chip1\_IBIAS7)

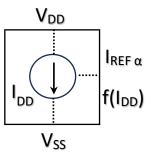
Ultra-Low-Power Reference Current with low TC. Proof of silicon with typical/preliminary measurements available. (Please contact <a href="mailto:sales@ailinear.com">sales@ailinear.com</a> for more information)

Parameter	Typical	Condition
	Spec	
I <sub>DD</sub> (nA)	~43	V <sub>DD</sub> =2v, Temperature = 27C
V <sub>DD</sub> Low (v)	~0.8	V <sub>DD</sub> sweep 0v→2.2v, Temperature = 27C
V <sub>DD</sub> High (v)	~2	V <sub>DD</sub> sweep 0v→2.2v, Temperature = 27C
TC (%/C)	~0.2	V <sub>DD</sub> =2v, ΔT ~30C
VC (%/V)	~0.3	V <sub>DD</sub> sweep 1v→2.2v, Temperature = 27C

\*See Disclaimer\*







I<sub>REF</sub> Cell Size ~76μm×74 μm in TSMC 180nm CMOS

## Features:

- Programmable (pre or post silicon) IREF that tracks IDD
- Tiny CMOS (~76μm×74 μm) bias current Intellectual Property (IP) cell operating in subthreshold with ultra-low current consumption I<sub>DD</sub> (typical 43nA)
- Large value but tiny active bias resistor (R<sub>PMOS</sub>) as a function of PMOSFET keeps I<sub>DD</sub> ultra-low
- Most suitable for SoC whose analog (e.g., oscillator, comparator, ADC) performance best correlates with PMOSFET parameters
- Suitable for SoC optimized for I<sub>REF</sub> voltage loop that is coupled to V<sub>DD</sub>
- I<sub>DD</sub> and I<sub>REF</sub> absolute value mostly a function of PMOSFET mobility (μ) inherently more stable to help narrow I<sub>DD</sub> variation over normal fabrication process corners
- Based on 180nm digital CMOS at TSMC and portable to smaller fabrication nodes.